Special Issue

Nanostructured Thermoelectrics; Synthesis, Processing and Applications

Message from the Guest Editors

This special issue aims at addressing different approaches of synthesis of bulk TE materials with nanoscale features and nanocomposites using methodologies ranging from solution phase synthesis to mechanochemical alloying/grinding techniques. Research on processing of these TE materials, as well TE devices made using nanostructured TEs, including hybrid materials or nanocomposites, are under the topics covered in this special issue due to their significance for paving the road from materials to niche TEG devices. Another focus of this special issue will be on theory and numerical simulation modeling extraordinary behaviors arising from nanostructuring, and simulation of nanostructured TE devices.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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